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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Salman Akram	§	Group Art Unit:	2827
Serial No.:	09/853,111	§		
Filed:	May 10, 2001	§	Examiner:	A. Chambliss
For:	Method of Fabricating Mounted Multiple Semiconductor Dies In A Package (As Amended)	§	Atty. Dkt. No.:	MCT.0012D1US (97-0141)

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO FINAL REJECTION

Sir:

In response to the Final Rejection, please amend the above-referenced patent application as follows:

Do not
enter this
amendment.
9/10/03

Date of Deposit: August 7, 2003

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.

Cynthia L. Hayden
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